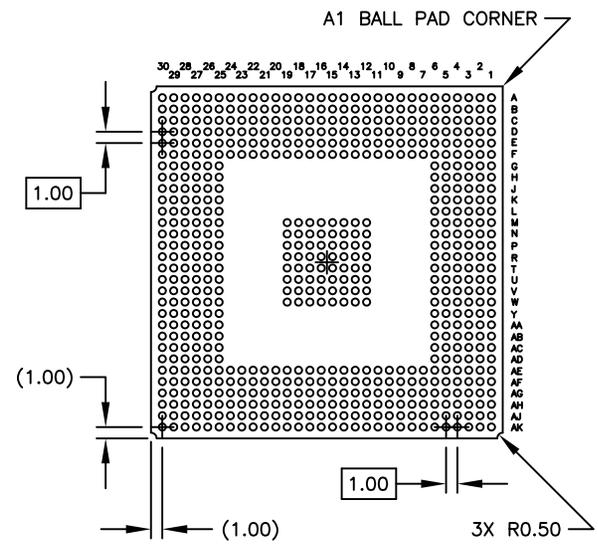
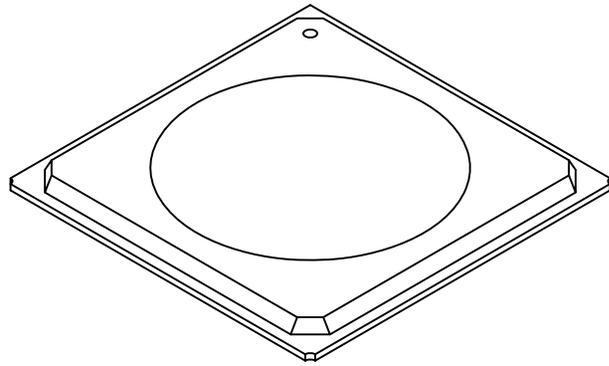


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	09/27/04	DP
01	UPDATE MOLD CAP SIZE	11/24/04	DP
02	COMBINE POD & LAND PATTERN	06/18/13	KS
03	UPDATE PACKAGE TO BHG	06/6/16	RT



8. THIS DRAWING CONFORMS TO THE JEDEC REGISTERED OUTLINE MS-034/A VARIATION AAN-1.



A1 BALL PAD CORNER I.D. FOR PLATE MOLD: TO BE MARKED BY INK.
AUTO MOLD: DIMPLE TO BE FORMED BY MOLD CAP.



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 900.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 30 X 30.

2. THE BASIC SOLDER BALL GRID PITCH IS 1.00mm.

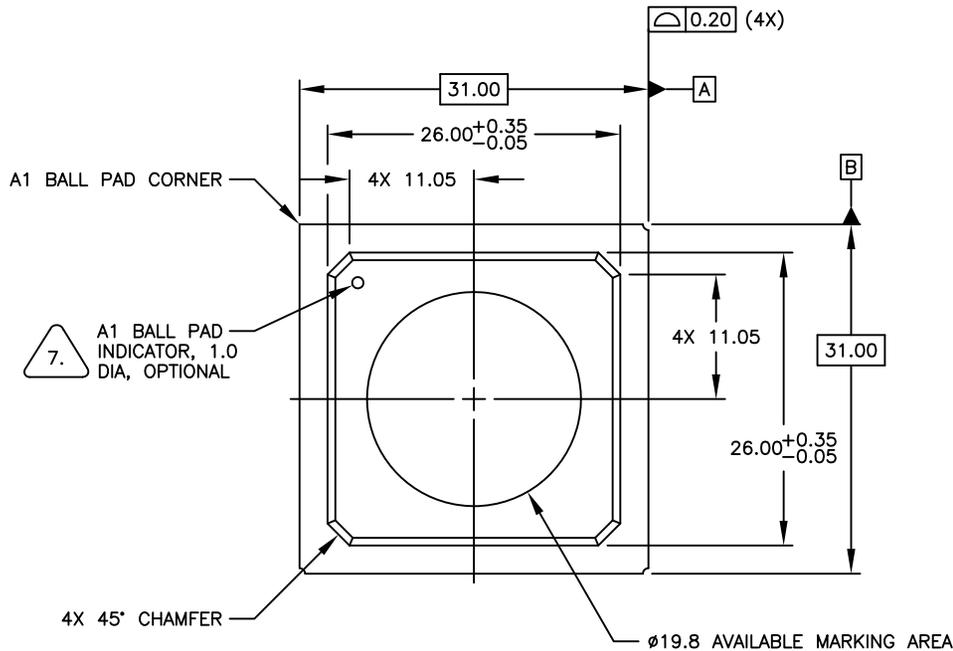
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

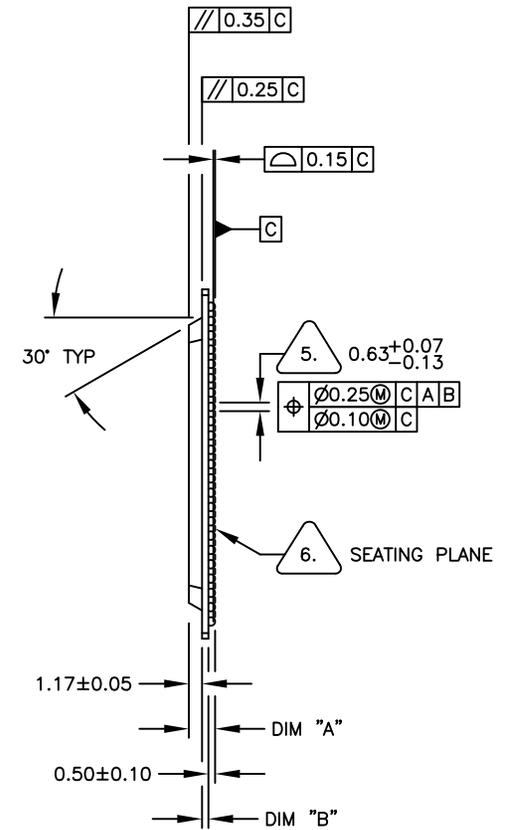
BOTTOM VIEW
640 SOLDER BALLS

TOLERANCES UNLESS SPECIFIED		 www.IDT.com	6024 SILVER CREEK VALLEY ROAD SAN JOSE, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-8591	
DECIMAL	ANGULAR			
X.X± 0.1	± 1°			
X.XX± 0.05				
X.XXX± 0.030				
APPROVALS	DATE	TITLE BHG 640 PACKAGE OUTLINE		
DRAWN <i>DP</i>	09/27/04	31.0 X 31.0 mm BODY		
CHECKED		1.00 mm PITCH TEPBGA		
		SIZE	DRAWING No.	REV
		C	PSC-4138	03
DO NOT SCALE DRAWING				SHEET 1 OF 3

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	09/27/04	DP
01	UPDATE MOLD CAP SIZE	11/24/04	DP
02	COMBINE POD & LAND PATTERN	06/18/13	KS
03	UPDATE PACKAGE TO BHG	06/6/16	RT



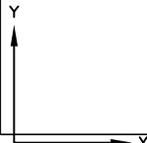
TOP VIEW



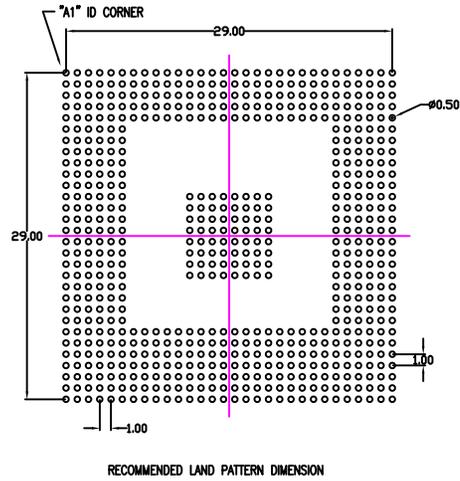
SIDE VIEW

NO. LAYERS	DIM "A"	DIM "B"	NOTES
4	2.23±0.21	0.56±0.06	STANDARD
TEPBGA-2 THICKNESS SCHEDULE			

TOLERANCES UNLESS SPECIFIED		 6024 SILVER CREEK VALLEY ROAD SAN JOSE, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-8591
DECIMAL	ANGULAR	
X.X ± 0.1	± 1°	
X.XX ± 0.05		
X.XXX ± 0.030		
APPROVALS	DATE	TITLE
DRAWN <i>DP</i>	09/27/04	BHG 640 PACKAGE OUTLINE 31.0 X 31.0 mm BODY 1.00 mm PITCH TEPBGA
CHECKED		
		SIZE
		DRAWING No.
		C
		PSC-4138
		REV
		03
DO NOT SCALE DRAWING		SHEET 2 OF 3



REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	09/27/04	DP
01	UPDATE MOLD CAP SIZE	11/24/04	DP
02	COMBINE POD & LAND PATTERN	06/18/13	KS
03	UPDATE PACKAGE TO BHG	06/6/16	RT



NOTE:

- 1) ALL dimensions are in mm. Angles in degrees.
- 2) Top down view, as view on PCB.
- 3) NSMD Land Pattern Assumed
- 4) Land Pattern Recommendation as per IPC-7351B generic requirement for surface mount design and Land Pattern.

TOLERANCES UNLESS SPECIFIED		 www.IDT.com	6024 SILVER CREEK VALLEY ROAD SAN JOSE, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-8591	
DECIMAL	ANGULAR			
X.X± 0.1	± 1°			
X.XX± 0.05				
X.XXX± 0.030				
APPROVALS	DATE	TITLE BHG 640 PACKAGE OUTLINE		
DRAWN <i>DP</i>	09/27/04	31.0 X 31.0 mm BODY		
CHECKED		1.00 mm PITCH TEPBGA		
		SIZE	DRAWING No.	REV
		C	PSC-4138	03
DO NOT SCALE DRAWING			SHEET 3 OF 3	